

MC10SX1189

Fibre Channel Coaxial Cable Driver and Loop Resiliency Circuit

Description

The MC10SX1189 is a differential receiver, differential transmitter specifically designed to drive coaxial cables. It incorporates the output cable drive capability of the MC10EL89 Coaxial Cable Driver with additional circuitry to multiplex the output cable drive source between the cable receiver or the local transmitter inputs. The multiplexer control circuitry is TTL compatible for ease of operation.

The MC10SX1189 is useful as a bypass element for Fibre Channel-Arbitrated Loop (FC-AL) or Serial Storage Architecture (SSA) applications, to create loop style interconnects with fault tolerant, active switches at each device node. This device is particularly useful for back panel applications where small size is desirable.

The EL89 style drive circuitry produces swings twice as large as a standard PECL output. When driving a coaxial cable, proper termination is required at both ends of the line to minimize reflections. The 1.6 V output swings allow for proper termination at both ends of the cable, while maintaining the required swing at the receiving end of the cable. Because of the larger output swings, the QT , \overline{QT} outputs are terminated into the thevenin equivalent of $50\ \Omega$ to $V_{CC} - 3.0\text{ V}$ instead of $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

Features

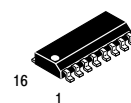
- 425 ps Propagation Delay
- 1.6 V Output Swing on the Cable Driving Output
- Operation Range:
 - ♦ $V_{CC} = 4.5\text{ V}$ to 5.5 V
- 75 k Ω Internal Input Pull Down Resistors
- >1000 V ESD Protection
- Transistor Count = 102
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



ON Semiconductor®

www.onsemi.com

FIBRE CHANNEL COAXIAL CABLE DRIVER AND LOOP RESILIENCY CIRCUIT



SOIC-16
CASE 751B-05

MARKING DIAGRAM*



10SX1189 = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping
MC10SX1189DG	SOIC-16 (Pb-Free)	48 Units/Tube

MC10SX1189

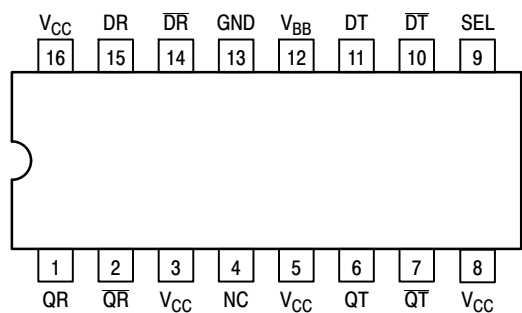


Figure 1. Pinout: SOIC-16 (Top View)

TRUTH TABLE

SEL	Function
L	DR → QT
H	DT → QT

PIN NAMES

Pins	Function
DR/ $\overline{\text{DR}}$	Differential Input from Receive Cable
QR/ $\overline{\text{QR}}$	Buffered Differential Output from Receive Cable
DT/ $\overline{\text{DT}}$	Differential Input to Transmit Cable
QT/ $\overline{\text{QT}}$	Buffered Differential Output to Transmit Cable
SEL	Multiplexer Control Signal (TTL)
V _{CC}	Positive Power Supply
GND	Ground
V _{BB}	Reference Voltage Output

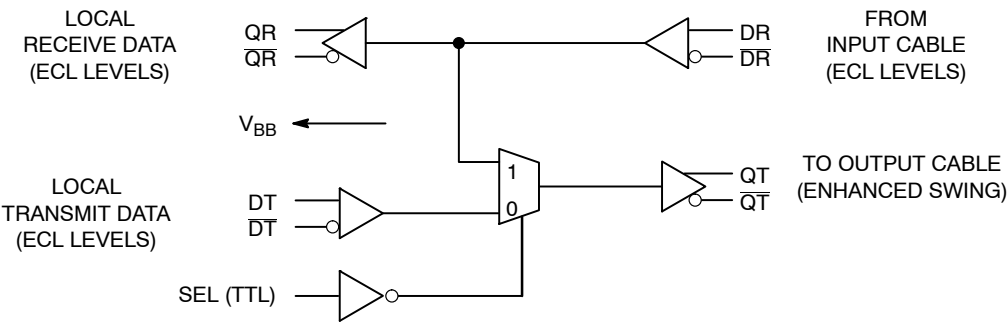


Figure 2. LOGIC DIAGRAM

Table 1. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Power Supply Voltage (Referenced to GND)	0 to +7.0	Vdc
V _{IN}	Input Voltage (Referenced to GND)	0 to +6.0	Vdc
I _{OUT}	Output Current Continuous Surge	50 100	mA
T _A	Operating Temperature Range	−40 to +85	°C
T _{STG}	Storage Temperature Range	−50 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MC10SX1189

Table 2. DC CHARACTERISTICS ($V_{CC} = 5.0\text{ V}$, $V_{EE} = 0\text{ V}$)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output Voltage High (QR, \overline{QR}) $V_{CC} = 5.0\text{ V}$, GND = 0 V (Notes 1, 2)	3.92	4.05	4.22	3.97	4.11	4.27	4.00	4.16	4.30	V
V_{OL}	Output Voltage Low (QR, \overline{QR}) $V_{CC} = 5.0\text{ V}$, GND = 0 V (Notes 1, 2)	3.05	3.23	3.35	3.07	3.24	3.37	3.10	3.25	3.41	V
V_{OH}	Output Voltage High (QT, \overline{QT}) $V_{CC} = 5.0\text{ V}$, GND = 0 V (Notes 1, 3)	3.83	3.95	4.10	3.88	4.02	4.15	3.90	4.09	4.17	V
V_{OL}	Output Voltage Low (QT, \overline{QT}) $V_{CC} = 5.0\text{ V}$, GND = 0 V (Notes 1, 3)	1.90	2.33	2.50	1.85	2.26	2.45	1.85	2.23	2.45	V
I_{CC}	Quiescent Supply Current (Note 4)	20	25	42	23	27	47	25	28	47	mA
V_{IH}	Input Voltage High (DR, \overline{DR} & DT, \overline{DT}) $V_{CC} = 5.0\text{ V}$, GND = 0 V (Note 1)	3.77		4.11	3.87		4.19	3.94		4.28	V
V_{IL}	Input Voltage Low (DR, \overline{DR} & DT, \overline{DT}) $V_{CC} = 5.0\text{ V}$, GND = 0 V (Note 1)	3.05		3.50	3.05		3.52	3.05		3.56	V
V_{IH}	Input Voltage High SEL	2.0			2.0			2.0			V
V_{IL}	Input Voltage Low SEL			0.8			0.8			0.8	V
V_{BB}	Output Reference Voltage $V_{CC} = 5.0\text{ V}$, GND = 0 V (Note 1)	3.57	3.63	3.70	3.65	3.70	3.75	3.69	3.75	3.81	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Values will track 1:1 with the V_{CC} supply. V_{EE} can vary +0.5 V to -0.5 V.
2. Outputs loaded with 50 Ω to $V_{CC} - 2.0\text{ V}$.
3. Outputs loaded with 50 Ω to $V_{CC} - 3.0\text{ V}$.
4. Outputs open circuited.

MC10SX1189

Table 3. AC CHARACTERISTICS ($V_{CC} = 4.5\text{ V to }5.5\text{ V}$) (Note 1)

Symbol	Characteristic	-40°C			0 to 85°C			Unit	Condition
		Min	Typ	Max	Min	Typ	Max		
t_{PLH} , t_{PHL}	Propagation Delay to Output DR → QR (Diff) (SE)	175	300	450	225	325	500	ps	Note 2 Note 3
	DR → QT (Diff) (SE)	150	300	500	175	325	550		
	DT → QT (Diff) (SE)	250	425	650	300	450	650		
	DT → QT (Diff) (SE)	225	425	700	250	450	700		
	DT → QT (Diff) (SE)	225	400	650	275	425	650		
	DT → QT (Diff) (SE)	200	400	725	225	425	725		
	Propagation Delay SEL → QT,QT	450	600	850	500	650	800		1.5V to 50% Pt
t_r , t_f	Rise TimeQR,QR Fall Time	100	275	400	125	275	400	ps	20% to 80%
	Fall Time	100	275	400	125	275	400		80% to 20%
t_r , t_f	Rise TimeQT,QT Fall Time	150	300	550	150	300	550	ps	20% to 80%
	Fall Time	150	300	550	150	300	550		80% to 20%
t_{skew}	Within Device Skew		15			15		ps	Note 4
V_{PP}	Minimum Input Swing	200		1000	200		1000	mV	Note 5
V_{CMR}	Common Mode Range	3.00		4.35	3.00		4.35	V	Note 6

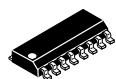
NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{EE} can vary +0.5 V to -0.5 V.
2. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals.
3. The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
4. Duty cycle skew is the difference between t_{PLH} and t_{PHL} propagation delay through a device.
5. Minimum input swing for which AC parameters are guaranteed.
6. The CMR range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between $V_{PP\text{ Min}}$ and 1.0 V.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

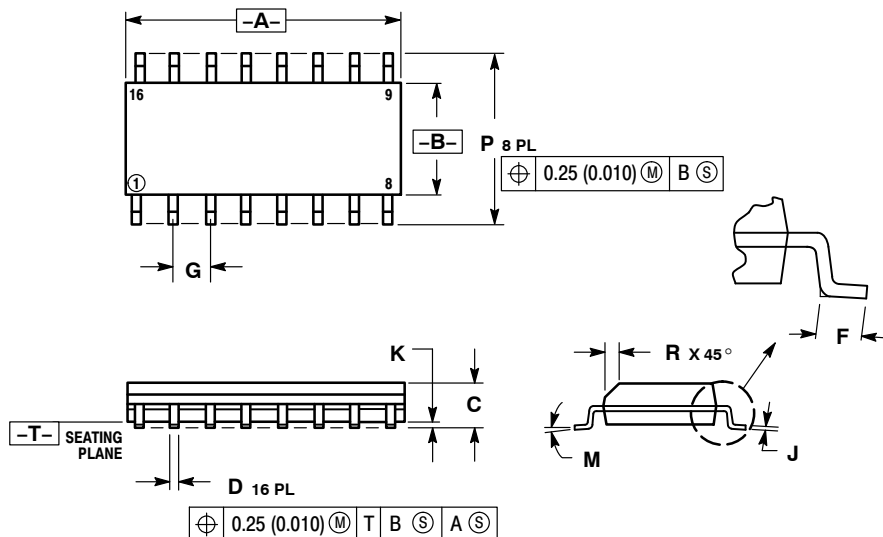
ON



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



NOTES:

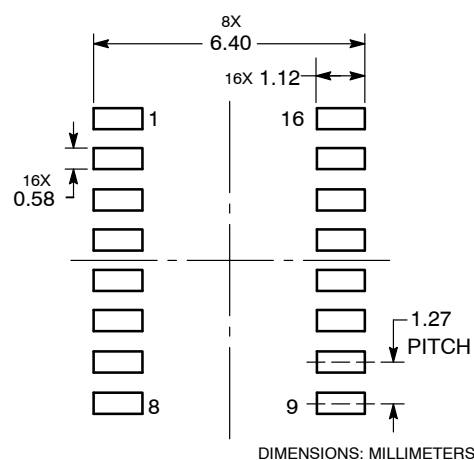
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:
PIN 1. COLLECTOR	PIN 1. CATHODE	PIN 1. COLLECTOR, DYE #1	PIN 1. COLLECTOR, DYE #1
2. BASE	2. ANODE	2. BASE, #1	2. COLLECTOR, #1
3. EMITTER	3. NO CONNECTION	3. EMITTER, #1	3. COLLECTOR, #2
4. NO CONNECTION	4. CATHODE	4. COLLECTOR, #1	4. COLLECTOR, #2
5. EMITTER	5. CATHODE	5. COLLECTOR, #2	5. COLLECTOR, #3
6. BASE	6. NO CONNECTION	6. BASE, #2	6. COLLECTOR, #3
7. COLLECTOR	7. ANODE	7. EMITTER, #2	7. COLLECTOR, #4
8. COLLECTOR	8. CATHODE	8. COLLECTOR, #2	8. COLLECTOR, #4
9. BASE	9. CATHODE	9. COLLECTOR, #3	9. BASE, #4
10. EMITTER	10. ANODE	10. BASE, #3	10. EMITTER, #4
11. NO CONNECTION	11. NO CONNECTION	11. EMITTER, #3	11. BASE, #3
12. EMITTER	12. CATHODE	12. COLLECTOR, #3	12. EMITTER, #3
13. BASE	13. CATHODE	13. COLLECTOR, #4	13. BASE, #2
14. COLLECTOR	14. NO CONNECTION	14. BASE, #4	14. EMITTER, #2
15. EMITTER	15. ANODE	15. EMITTER, #4	15. BASE, #1
16. COLLECTOR	16. CATHODE	16. COLLECTOR, #4	16. EMITTER, #1

STYLE 5:	STYLE 6:	STYLE 7:
PIN 1. DRAIN, DYE #1	PIN 1. CATHODE	PIN 1. SOURCE N-CH
2. DRAIN, #1	2. CATHODE	2. COMMON DRAIN (OUTPUT)
3. DRAIN, #2	3. CATHODE	3. COMMON DRAIN (OUTPUT)
4. DRAIN, #2	4. CATHODE	4. GATE P-CH
5. DRAIN, #3	5. CATHODE	5. COMMON DRAIN (OUTPUT)
6. DRAIN, #3	6. CATHODE	6. COMMON DRAIN (OUTPUT)
7. DRAIN, #4	7. CATHODE	7. COMMON DRAIN (OUTPUT)
8. DRAIN, #4	8. CATHODE	8. SOURCE P-CH
9. GATE, #4	9. ANODE	9. SOURCE P-CH
10. SOURCE, #4	10. ANODE	10. COMMON DRAIN (OUTPUT)
11. GATE, #3	11. ANODE	11. COMMON DRAIN (OUTPUT)
12. SOURCE, #3	12. ANODE	12. COMMON DRAIN (OUTPUT)
13. GATE, #2	13. ANODE	13. GATE N-CH
14. SOURCE, #2	14. ANODE	14. COMMON DRAIN (OUTPUT)
15. GATE, #1	15. ANODE	15. COMMON DRAIN (OUTPUT)
16. SOURCE, #1	16. ANODE	16. SOURCE N-CH

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

DOCUMENT NUMBER:	98ASB42566B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-16	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

